

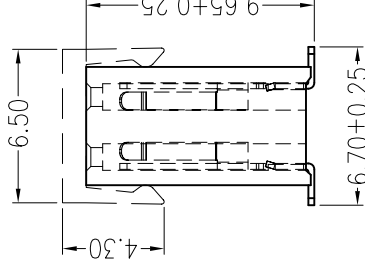
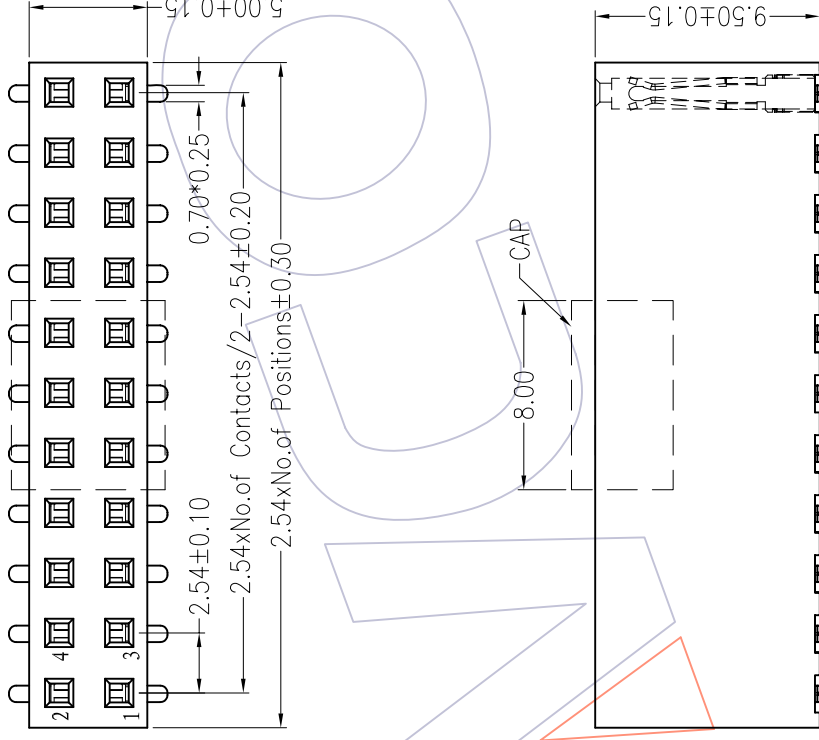
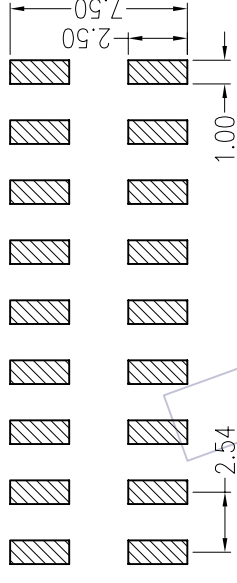
HSF

Recommended P.C.B Layout(Top Side) (PCB BOARD TOLERANCE±0.05)

NOTES:

Rated Current:3.0AMP
 Contact Resistance:20mΩ max
 Withstand Voltage:1000V AC/DC
 Insulation Resistance:1000MΩ min
 Operation Temperature:-40°C to +105°C

Contact Material:Phosphor Bronze
 Contact Plating: Au or Sn Over Ni
 Insulator Material:PA6T+30%G.F(UL94V-0)



Ordering Information

2195 - 2 XX M XX X UN X 1

No.of Pins Per 02-40P	Contact Plating G0=Gold Flash G1=3µ"Gold G2=5µ"Gold G3=10µ"Gold G4=15µ"Gold G5=30µ"Gold S0=Gold Flash/Tin S1=3µ"Gold/Tin S2=5µ"Gold/Tin S3=10µ"Gold/Tin S4=15µ"Gold/Tin S5=30µ"Gold/Tin SN=Tin	Insulator C=PA6T D=LCP	Packing T=Tube P=Tube+CAP R=Tape&Reel+CAP
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WCON 维峰五金电子有限公司 WAFE HARDWARE ELECTRONICS CO.,LTD		SCALE 1:1	09.02.13	WEIXD	DRAW	OPERATION	DRAW		WEIXD	09.02.13	SCALE 1:1	WCON 维峰五金电子有限公司 WAFE HARDWARE ELECTRONICS CO.,LTD	
A0	09/02/13	UNIT mm		DESIGN	DESIGN	X.X ±0.40		DESIGN			UNIT mm	2195-2XXMXXUNX1	
		SIZE A4		CHECK	CHECK	X.XXX ±0.25		CHECK			SIZE A4	PART NO.	
		SHEET 1/1		APPROVE	APPROVE	X.XXX ±0.15		APPROVE			SHEET 1/1	TITLE:	
REV	DATE	PROJ.				Angle DIM ±.3°					PROJ.	Customer NO.	
						DIM TOL							

1 2 3 4 5 6 7 8 9 10